

What is claimed is:

1. A coupling arrangement for coupling the same semiconductor device to different models of semiconductor device testers manufactured by different manufacturers, the arrangement comprising:

a mother board electrically compatible with each of respective test heads of the different models of testers; and

a device under test (DUT) board connectable between the mother board and a semiconductor device to be tested by one of the different models of tester.

2. The coupling arrangement of claim 1 further comprising:

a load board loading unit to mechanically bind the mother board to any one of the test heads.

3. The coupling arrangement of claim 1, wherein the mother board provides signal paths for mixed signals, respectively.

4. The coupling arrangement of claim 1, wherein a plurality of locking units are placed on the mother board for mechanically connecting the DUT board to the mother board.

5. The coupling arrangement of claim 4, wherein an electrical connection between the respective test head and the semiconductor device is made through a connector on the mother board.

6. The semiconductor element tester of claim 4, wherein the plurality of locking units has the same shape regardless of the particular manufacturer of the tester.

7. The semiconductor device tester of claim 1, wherein the DUT board includes vertical type relays.

8. A method of making one or more test connections between one kind of semiconductor device and any one of multiple testers from different manufacturers that are each operable upon the one kind of semiconductor device, the method comprising:

providing a mother board electrically compatible with each of respective test heads of the different testers;

providing a device under test (DUT) board connectable between the mother board and the one kind of semiconductor device to be tested;

coupling any one of the respective test heads to the mother board;

coupling the DUT board to the mother board; and

coupling the one kind of semiconductor device to the DUT board.

9. The coupling arrangement of claim 1, further comprising:

mechanically binding the mother board heads via a load board loading unit.

10. The method of claim 8, wherein the mother board provides signal paths for different models of testers of mixed signals, respectively.

11. The method of claim 8, further comprising binding the DUT board to the mother board via a plurality of locking units.

12. The coupling arrangement of claim 1, further comprising:

arranging a first side of the mother board to have terminals for test signal paths distributed azimuthally around the center thereof, and arranging a second side of the mother board to have terminals for test signal paths, respectively, gathered into a relative smaller predetermined area.

13. The coupling arrangement of claim 12, wherein the predetermined area is arcuate in shape.

14. The method of claim 8, further comprising electrically connecting test signal paths through the mother board to test signal paths on the DUT board via aligning conductive terminals.